ABSTRACT

SEMICONDUCTOR COMPONENT HAVING CHIP ON BOARD LEADFRAME AND METHOD OF FABRICATION

A semiconductor component includes a chip on board leadframe, a semiconductor die back bonded and wire bonded to the leadframe, an encapsulant on the die and an area array of terminal contacts on the leadframe. The leadframe includes leadfingers, interconnect bonding sites for wire bonding the die, terminal bonding sites for the terminal contacts, and bus bars which electrically connect selected leadfingers to one another. The interconnect bonding sites are located on the leadframe relative to the bus bars such that shorting to the bus bars by wire interconnects is eliminated. A method for fabricating the component includes the steps of attaching the die to the leadframe, bonding the wire interconnects to the die and to the interconnect bonding sites, forming the encapsulant, and then forming the terminal contacts on the terminal bonding sites.

FIGURE 1A